- **Power Dissipation . . . 40 mW Max**
- **Advanced LinEPIC™ Single-Poly Process Provides Close Capacitor Matching for Better Accuracy**
- **Fast Parallel Processing for DSP and μP Interface**
- **Either External or Internal Clock Can Be Used**
- **Conversion Time . . . 6 μs**
- **Total Unadjusted Error . . . ±1 LSB Max**
- **CMOS Technology**

description

The TLC1550x and TLC1551 are data acquisition analog-to-digital converters (ADCs) using a 10-bit, switched-capacitor, successive-approximation network. A high-speed, 3-state parallel port directly interfaces to a digital signal processor (DSP) or microprocessor (μP) system data bus. D0 through D9 are the digital output terminals with D0 being the least significant bit (LSB). Separate power terminals for the analog and digital portions minimize noise pickup in the supply leads. Additionally, the digital power is divided into two parts to separate the lower current logic from the higher current bus drivers. An external clock can be applied to CLKIN to override the internal system clock if desired.

The TLC1550I and TLC1551I are characterized for operation from −40°C to 85°C. The TLC1550M is characterized over the full military range of −55°C to 125°C.

J† OR DW PACKAGE
(TOP VIEW)

REF+	1		24	$\overline{RD}$
REF−	2		23	$\overline{WR}$
ANLG GND	3		22	CLKIN
AIN	4		21	$\overline{CS}$
ANLG V_{DD}	5		20	D9
DGTL GND1	6		19	D8
DGTL GND2	7		18	D7
DGTL V_{DD1}	8		17	D6
DGTL V_{DD2}	9		16	D5
EOC	10		15	D4
D0	11		14	D3
D1	12		13	D2
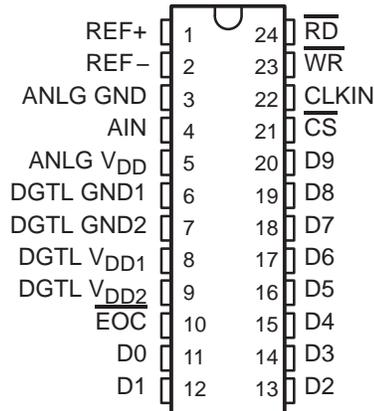
† Refer to the mechanical data for the JW package.

FK OR FN PACKAGE
(TOP VIEW)

Top pins (left to right): ANLG GND 4, REF− 3, REF+ 2, NC 1, $\overline{RD}$ 28, $\overline{WR}$ 27, CLKIN 26

AIN	5		25	$\overline{CS}$
ANLG V_{DD}	6		24	D9
DGTL GND1	7		23	D8
NC	8		22	NC
DGTL GND2	9		21	D7
DGTL V_{DD1}	10		20	D6
DGTL V_{DD2}	11		19	D5

Bottom pins (left to right): EOC 12, D0 13, D1 14, NC 15, D2 16, D3 17, D4 18
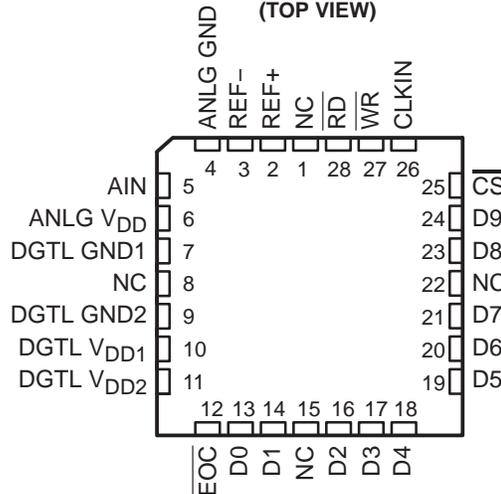
NC – No internal connection

AVAILABLE OPTIONS

T_A	PACKAGE			
	CERAMIC CHIP CARRIER (FK)	PLASTIC CHIP CARRIER (FN)	CERAMIC DIP (J)	SOIC (DW)
−40°C to 85°C	—	TLC1550IFN TLC1551IFN	—	TLC1550IDW TLC1551IDW
−55°C to 125°C	TLC1550MFK	—	TLC1550MJ	—

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TEXAS INSTRUMENTS

functional block diagram

typical equivalent inputs
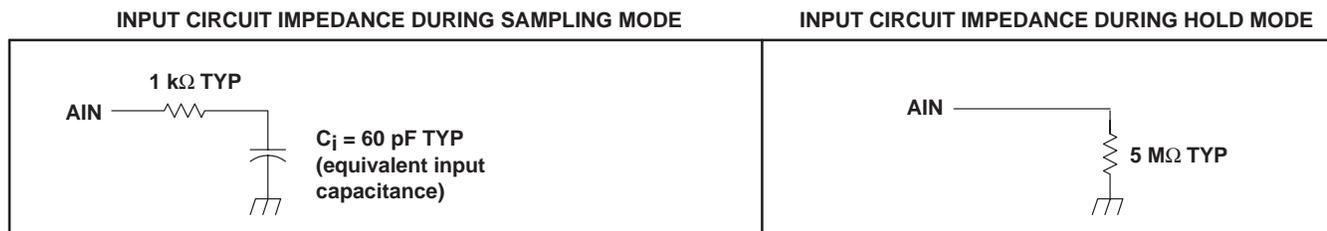
INPUT CIRCUIT IMPEDANCE DURING SAMPLING MODE

INPUT CIRCUIT IMPEDANCE DURING HOLD MODE

Terminal Functions

TERMINAL			DESCRIPTION
NAME	NO.[†]	NO.[‡]	
ANLG GND	4	3	Analog ground. The reference point for the voltage applied on terminals ANLG V_{DD}, AIN, REF+, and REF–.
AIN	5	4	Analog voltage input. The voltage applied to AIN is converted to the equivalent digital output.
ANLG V_{DD}	6	5	Analog positive power supply voltage. The voltage applied to this terminal is designated V_{DD3}.
CLKIN	26	22	Clock input. CLKIN is used for external clocking instead of using the internal system clock. It usually takes a few microseconds before the internal clock is disabled. To use the internal clock, CLKIN should be tied high or left unconnected.
$\overline{CS}$	25	21	Chip-select. $\overline{CS}$ must be low for $\overline{RD}$ or $\overline{WR}$ to be recognized by the A/D converter.
D0	13	11	Data bus output. D0 is bit 1 (LSB).
D1	14	12	Data bus output. D1 is bit 2.
D2	16	13	Data bus output. D2 is bit 3.
D3	17	14	Data bus output. D3 is bit 4.
D4	18	15	Data bus output. D4 is bit 5.
D5	19	16	Data bus output. D5 is bit 6.
D6	20	17	Data bus output. D6 is bit 7.
D7	21	18	Data bus output. D7 is bit 8.
D8	23	19	Data bus output. D8 is bit 9.
D9	24	20	Data bus output. D9 is bit 10 (MSB).
DGTL GND1	7	6	Digital ground 1. The ground for power supply DGTL V_{DD1} and is the substrate connection
DGTL GND2	9	7	Digital ground 2. The ground for power supply DGTL V_{DD2}
DGTL V_{DD1}	10	8	Digital positive power-supply voltage 1. DGTL V_{DD1} supplies the logic. The voltage applied to DGTL V_{DD1} is designated V_{DD1}.
DGTL V_{DD2}	11	9	Digital positive power-supply voltage 2. DGTL V_{DD2} supplies only the higher-current output buffers. The voltage applied to DGTL V_{DD2} is designated V_{DD2}.
$\overline{EOC}$	12	10	End-of-conversion. $\overline{EOC}$ goes low indicating that conversion is complete and the results have been transferred to the output latch. $\overline{EOC}$ can be connected to the µP- or DSP-interrupt terminal or can be continuously polled.
$\overline{RD}$	28	24	Read input. When $\overline{CS}$ is low and $\overline{RD}$ is taken low, the data is placed on the data bus from the output latch. The output latch stores the conversion results at the most recent negative edge of $\overline{EOC}$. The falling edge of $\overline{RD}$ resets $\overline{EOC}$ to a high within the $t_{d(EOC)}$ specifications.
REF+	2	1	Positive voltage-reference input. Any analog input that is greater than or equal to the voltage on REF+ converts to 1111111111. Analog input voltages between REF+ and REF– convert to the appropriate result in a ratiometric manner.
REF–	3	2	Negative voltage reference input. Any analog input that is less than or equal to the voltage on REF– converts to 0000000000.
$\overline{WR}$	27	23	Write input. When $\overline{CS}$ is low, conversion is started on the rising edge of $\overline{WR}$. On this rising edge, the ADC holds the analog input until conversion is completed. Before and after the conversion period, which is given by t_{conv}, the ADC remains in the sampling mode.

† Terminal numbers for FK and FN packages.
‡ Terminal numbers for J, DW, and NW packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD1}, V_{DD2}, and V_{DD3} (see Note 1) . . . . 6.5 V
Input voltage range, V_I (any input) . . . . −0.3 V to V_{DD} + 0.3 V
Output voltage range, V_O . . . . −0.3 V to V_{DD} + 0.3 V
Peak input current (any digital input) . . . . ±10 mA
Peak total input current (all inputs) . . . . ±30 mA
Operating free-air temperature range, T_A: TLC1550I, TLC1551I . . . . −40°C to 85°C
TLC1550M . . . . −55°C to 125°C
Storage temperature range, T_{stg} . . . . −65°C to 150°C
Case temperature for 10 seconds: FK or FN package . . . . 260°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds: J or NW package . . . . 260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
  functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
  implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: V_{DD1} is the voltage measured at DGTL V_{DD1} with respect to DGND1. V_{DD2} is the voltage measured at DGTL V_{DD2} with respect to the
          DGND2. V_{DD3} is the voltage measured at ANLG V_{DD} with respect to AGND. For these specifications, all ground terminals are tied
          together (and represent 0 V). When V_{DD1}, V_{DD2}, and V_{DD3} are equal, they are referred to simply as V_{DD}.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{DD1}, V_{DD2}, V_{DD3}		4.75	5	5.5	V
Positive reference voltage, V_{REF+} (see Note 2)			V_{DD3}		V
Negative reference voltage, V_{REF-} (see Note 2)			0		V
Differential reference voltage, $V_{REF+} - V_{REF-}$ (see Note 2)				V_{DD3}	V
Analog input voltage range		0		V_{DD3}	V
High-level control input voltage, V_{IH}		2			V
Low-level control input voltage, V_{IL}				0.8	V
Input clock frequency, $f_{(CLKIN)}$		0.5		7.8	MHz
Setup time, $\overline{CS}$ low before $\overline{WR}$ or $\overline{RD}$ goes low, $t_{su(CS)}$		0			ns
Hold time, $\overline{CS}$ low after $\overline{WR}$ or $\overline{RD}$ goes high, $t_{h(CS)}$		0			ns
$\overline{WR}$ or $\overline{RD}$ pulse duration, $t_{w(WR)}$		50			ns
Input clock low pulse duration, $t_{w(L–CLKIN)}$		40% of period		80% of period	
Operating free-air temperature, T_A	TLC155xI	−40		85	°C
	TLC1550M	−55		125	

NOTE 2:   Analog input voltages greater than that applied to REF+ convert to all 1s (1111111111), while input voltages less than that applied to
          REF– convert to all 0s (0000000000). The total unadjusted error may increase as this differential voltage falls below 4.75 V.

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electrical characteristics over recommended operating free-air temperature range,
$V_{DD} = V_{REF+}$ = 4.75 V to 5.5 V and V_{REF-} = 0 (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	V_{DD} = 4.75 V,	I_{OH} = −360 µA	2.4			V
V_{OL}	Low-level output voltage	V_{DD} = 4.75 V, I_{OL} = 2.4 mA	T_A = 25°C			0.4	V
			T_A = −55°C to 125°C			0.5	
I_{OZ}	Off-state (high-impedance-state) output current	$V_O = V_{DD}$,	$\overline{CS}$ and $\overline{RD}$ at V_{DD}			10	µA
		V_O = 0,	$\overline{CS}$ and $\overline{RD}$ at V_{DD}			−10	
I_{IH}	High-level input current	$V_I = V_{DD}$			0.005	2.5	µA
I_{IL}	Low-level input current (except CLKIN)	V_I = 0		−2.5	−0.005		µA
I_{IL}	Low-level input current (CLKIN)			−50	−50		µA
I_{OS}	Short-circuit output current	V_O = 5 V,	T_A = 25°C	7	14		mA
		V_O = 0,	T_A = 25°C		−12	−6	
$I_{(DD)}$	Operating supply current	$\overline{CS}$ low and $\overline{RD}$ high			2	8	mA
C_i	Input capacitance	Analog inputs	See typical equivalent inputs TLC1550/1I		60	90*	pF
		Digital inputs			5	15*	

* On products compliant to MIL-STD-883, Class B, this parameter is not production tested.
† All typical values are at V_{DD} = 5 V, T_A = 25°C.

operating characteristics over recommended operating free-air temperature range with internal clock and minimum sampling time of 4 μs, V_{DD} = V_{REF+} = 5 V and V_{REF-} = 0 (unless otherwise noted)

PARAMETER			TEST CONDITIONS	T_A†	MIN	TYP‡	MAX	UNIT
E_L	Linearity error	TLC1550I	See Note 3	Full range			±0.5	LSB
		TLC1551I		Full range			±1	
		TLC1550M		25°C			±0.5	
				Full range			±1	
E_{ZS}	Zero-scale error	TLC1550I	See Notes 2 and 4	Full range			±0.5	LSB
		TLC1551I		Full range			±1	
		TLC1550M		25°C			±0.5	
				Full range			±1	
E_{FS}	Full-scale error	TLC1550I	See Notes 2 and 4	Full range			±0.5	LSB
		TLC1551I		Full range			±1	
		TLC1550M		25°C			±0.5	
				Full range			±1	
	Total unadjusted error	TLC1550I	See Note 5	Full range			±0.5	LSB
		TLC1551I		Full range			±1	
		TLC1550M		25°C			±1	
t_c	Conversion time		$f_{clock(external)}$ = 4.2 MHz or internal clock				6	μs
$t_{a(D)}$	Data access time after $\overline{RD}$ goes low		See Figure 3				35	ns
$t_{V(D)}$	Data valid time after $\overline{RD}$ goes high					5		ns
$t_{dis(D)}$	Disable time, delay time from $\overline{RD}$ high to high impedance						30	ns
$t_{d(EOC)}$	Delay time, $\overline{RD}$ low to $\overline{EOC}$ high					0	15	ns

† Full range is −40°C to 85°C for the TL155xI devices and −55°C to 125°C for the TLC1550M.
‡ All typical values are at V_{DD} = 5 V, T_A = 25°C.
NOTES: 2. Analog input voltages greater than that applied to REF+ convert to all 1s (1111111111), while input voltages less than that applied to REF− convert to all 0s (0000000000). The total unadjusted error may increase as this differential voltage falls below 4.75 V.
3. Linearity error is the difference between the actual analog value at the transition between any two adjacent steps and its ideal value after zero-scale error and full-scale error have been removed.
4. Zero-scale error is the difference between the actual mid-step value and the nominal mid-step value at specified zero scale. Full-scale error is the difference between the actual mid-step value and the nominal mid-step value at specified full scale.
5. Total unadjusted error is the difference between the actual analog value at the transition between any two adjacent steps and its ideal value. It includes contributions from zero-scale error, full-scale error, and linearity error.

PARAMETER MEASUREMENT INFORMATION
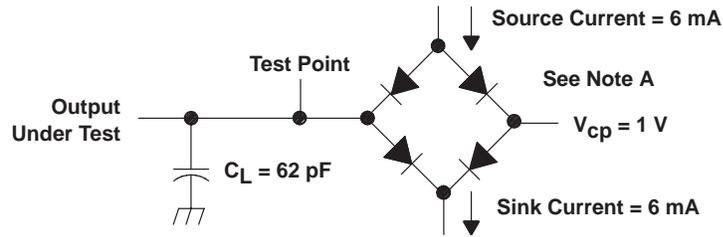
V_{cp} = **voltage commutation point for switching between source and sink currents**

NOTE A: Equivalent load circuit of the Teradyne A500 tester for timing parameter measurement

Figure 1. Test Load Circuit

APPLICATION INFORMATION

simplified analog input analysis

Using the circuit in Figure 2, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S\left(1 - e^{-t_c/R_t C_i}\right) \tag{1}$$

Where:

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C \text{ (1/2 LSB)} = V_S - (V_S/1024) \tag{2}$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - \left(V_S/512\right) = V_S\left(1 - e^{-t_c/R_t C_i}\right) \tag{3}$$

and

$$t_c \text{ (1/2 LSB)} = R_t \times C_i \times \ln(1024) \tag{4}$$

Therefore, with the values given, the time for the analog input signal to settle is

$$t_c \text{ (1/2 LSB)} = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(1024) \tag{5}$$

This time must be less than the converter sample time shown in the timing diagrams.
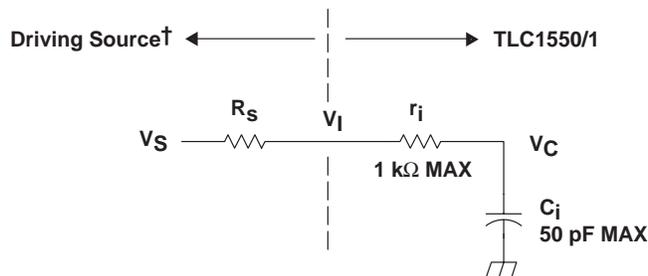
V_I = Input voltage at AIN
V_S = External driving source voltage
R_s = Source resistance
r_i = Input resistance
C_i = Input capacitance

† Driving source requirements:
- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 2. Input Circuit Including the Driving Source

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PRINCIPLES OF OPERATION

The operating sequence for complete data acquisition is shown in Figure 3. Processors can address the TLC1550 and TLC1551 as an external memory device by simply connecting the address lines to a decoder and the decoder output to $\overline{CS}$. Like other peripheral devices, the write ($\overline{WR}$) and read ($\overline{RD}$) input signals are valid only when $\overline{CS}$ is low. Once $\overline{CS}$ is low, the onboard system clock permits the conversion to begin with a simple write command and the converted data to be presented to the data bus with a simple read command. The device remains in a sampling (track) mode from the rising edge of $\overline{EOC}$ until conversion begins with the rising edge of $\overline{WR}$, which initiates the hold mode. After the hold mode begins, the clock controls the conversion automatically. When the conversion is complete, the end-of-conversion ($\overline{EOC}$) signal goes low indicating that the digital data has been transferred to the output latch. Lowering $\overline{CS}$ and $\overline{RD}$ then resets $\overline{EOC}$ and transfers the data to the data bus for the processor read cycle.
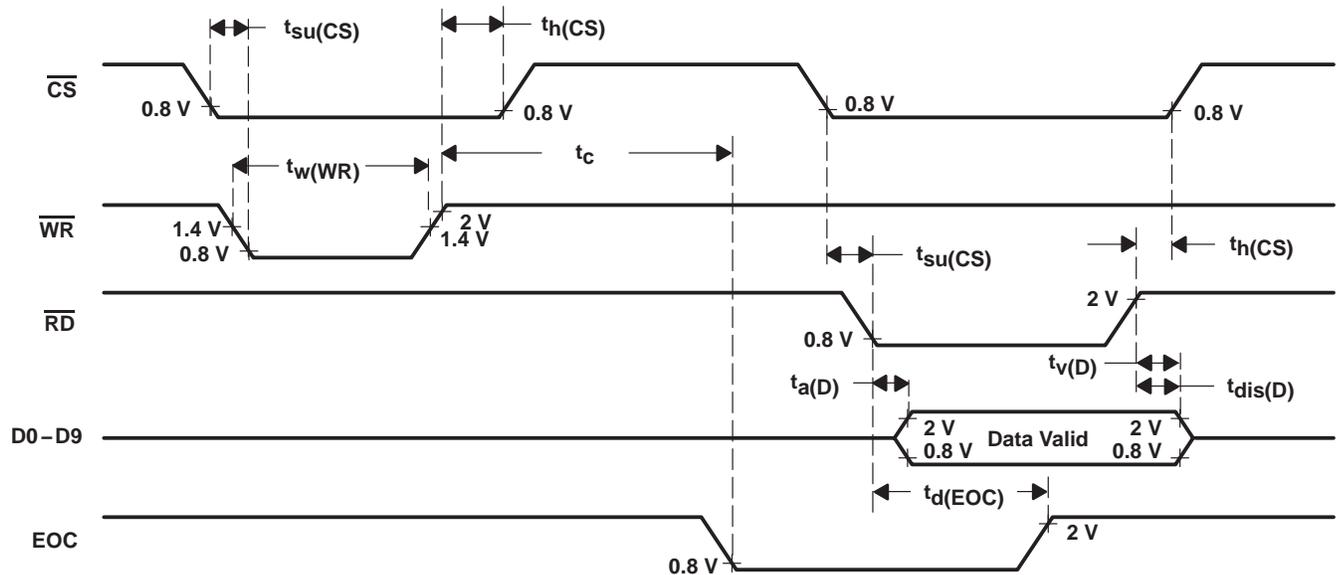
Figure 3. TLC1550 or TLC1551 Operating Sequence

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC1550IDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1550I	Samples
TLC1550IDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1550I	Samples
TLC1550IDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1550I	Samples
TLC1550IFN	ACTIVE	PLCC	FN	28	37	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1550IFN	Samples
TLC1550INW	OBSOLETE	PDIP	NW	24		TBD	Call TI	Call TI	-40 to 85		
TLC1550MFKB	OBSOLETE	LCCC	FK	28		TBD	Call TI	Call TI	-55 to 125		
TLC1550MJ	OBSOLETE	CDIP	J	24		TBD	Call TI	Call TI	-55 to 125		
TLC1550MJB	OBSOLETE	CDIP	J	24		TBD	Call TI	Call TI	-55 to 125		
TLC1551IDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1551I	Samples
TLC1551IDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1551I	Samples
TLC1551IDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1551I	Samples
TLC1551IFN	ACTIVE	PLCC	FN	28	37	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1551IFN	Samples
TLC1551IFNG4	ACTIVE	PLCC	FN	28	37	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC1551IFN	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC1550IDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
TLC1551IDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC1550IDWR	SOIC	DW	24	2000	367.0	367.0	45.0
TLC1551IDWR	SOIC	DW	24	2000	367.0	367.0	45.0

MECHANICAL DATA

J (R-GDIP-T**) **CERAMIC DUAL-IN-LINE PACKAGE**

24 PINS SHOWN

0.065 (1,65)
0.045 (1,14)

0.090 (2,29)
0.060 (1,53)

0.175 (4,45)
0.140 (3,56)

Lens Protrusion (Lens Optional)
0.010 (0.25) MAX

A

Seating Plane

0.018 (0,46) MIN

0.125 (3,18) MIN

0.100 (2,54)

0.022 (0,56)
0.014 (0,36)

0.012 (0,30)
0.008 (0,20)

DIM	PINS **	24		28		32		40	
		NARR	WIDE	NARR	WIDE	NARR	WIDE	NARR	WIDE
"A"	MAX	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)
	MIN	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)
"B"	MAX	1.265(32,13)	1.265(32,13)	1.465(37,21)	1.465(37,21)	1.668(42,37)	1.668(42,37)	2.068(52,53)	2.068(52,53)
	MIN	1.235(31,37)	1.235(31,37)	1.435(36,45)	1.435(36,45)	1.632(41,45)	1.632(41,45)	2.032(51,61)	2.032(51,61)
"C"	MAX	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)
	MIN	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)

4040084/C 10/97

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).
D. This package can be hermetically sealed with a ceramic lid using glass frit.
E. Index point is provided on cap for terminal identification.

TEXAS
INSTRUMENTS
POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

FK (S−CQCC−N**)   LEADLESS CERAMIC CHIP CARRIER
28 TERMINAL SHOWN
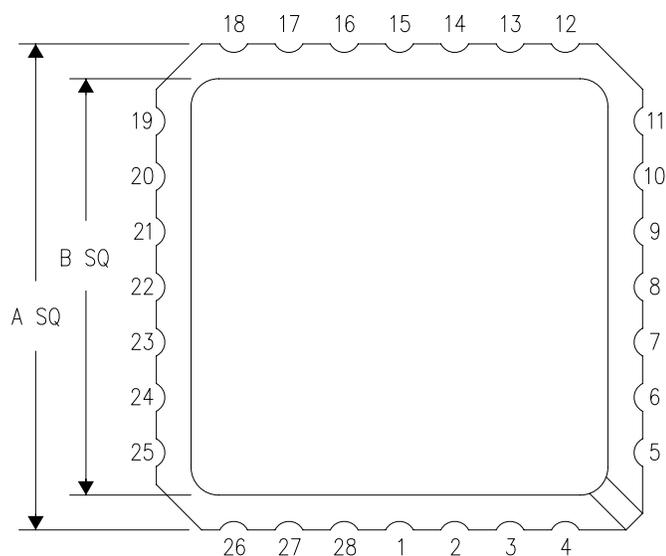
NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

$\dfrac{0.020\ (0,51)}{0.010\ (0,25)}$

$\dfrac{0.020\ (0,51)}{0.010\ (0,25)}$

$\dfrac{0.080\ (2,03)}{0.064\ (1,63)}$

$\dfrac{0.055\ (1,40)}{0.045\ (1,14)}$

$\dfrac{0.045\ (1,14)}{0.035\ (0,89)}$

$\dfrac{0.028\ (0,71)}{0.022\ (0,54)}$

0.050 (1,27)

$\dfrac{0.045\ (1,14)}{0.035\ (0,89)}$
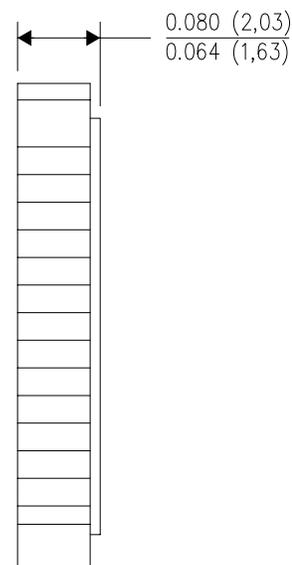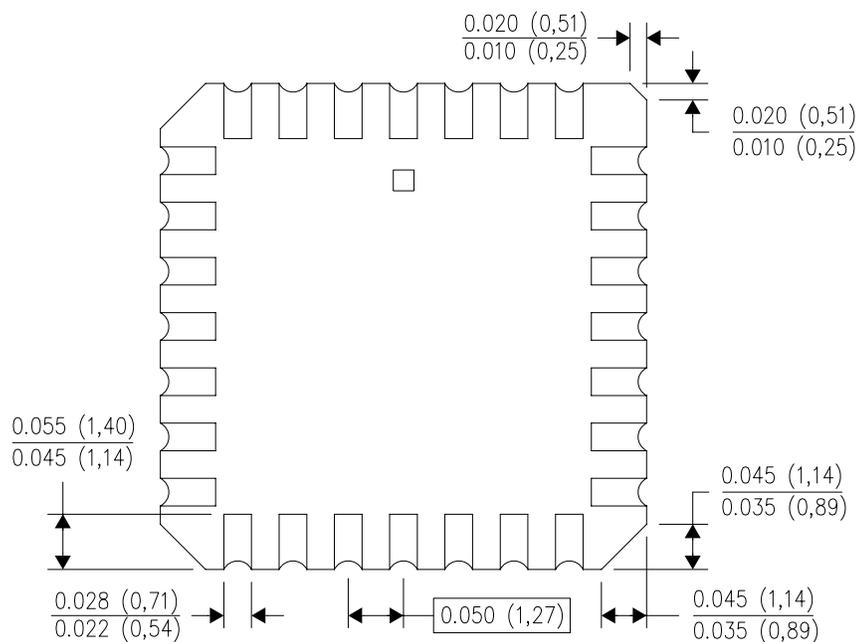
4040140/D 01/11

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a metal lid.
         D.   Falls within JEDEC MS−004

TEXAS INSTRUMENTS
www.ti.com

DW (R−PDSO−G24)   PLASTIC SMALL OUTLINE

0.614 (15,60)
0.598 (15,20)

24   13

0.419 (10,63)
0.393 (9,97)

0.299 (7,60)
0.291 (7,40)

1   12

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.104 (2,65) Max

0.012 (0,30)
0.004 (0,10)

0.013 (0,33)
0.008 (0,20)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°–8°

0.050 (1,27)
0.016 (0,40)

4040000−5/G 01/11
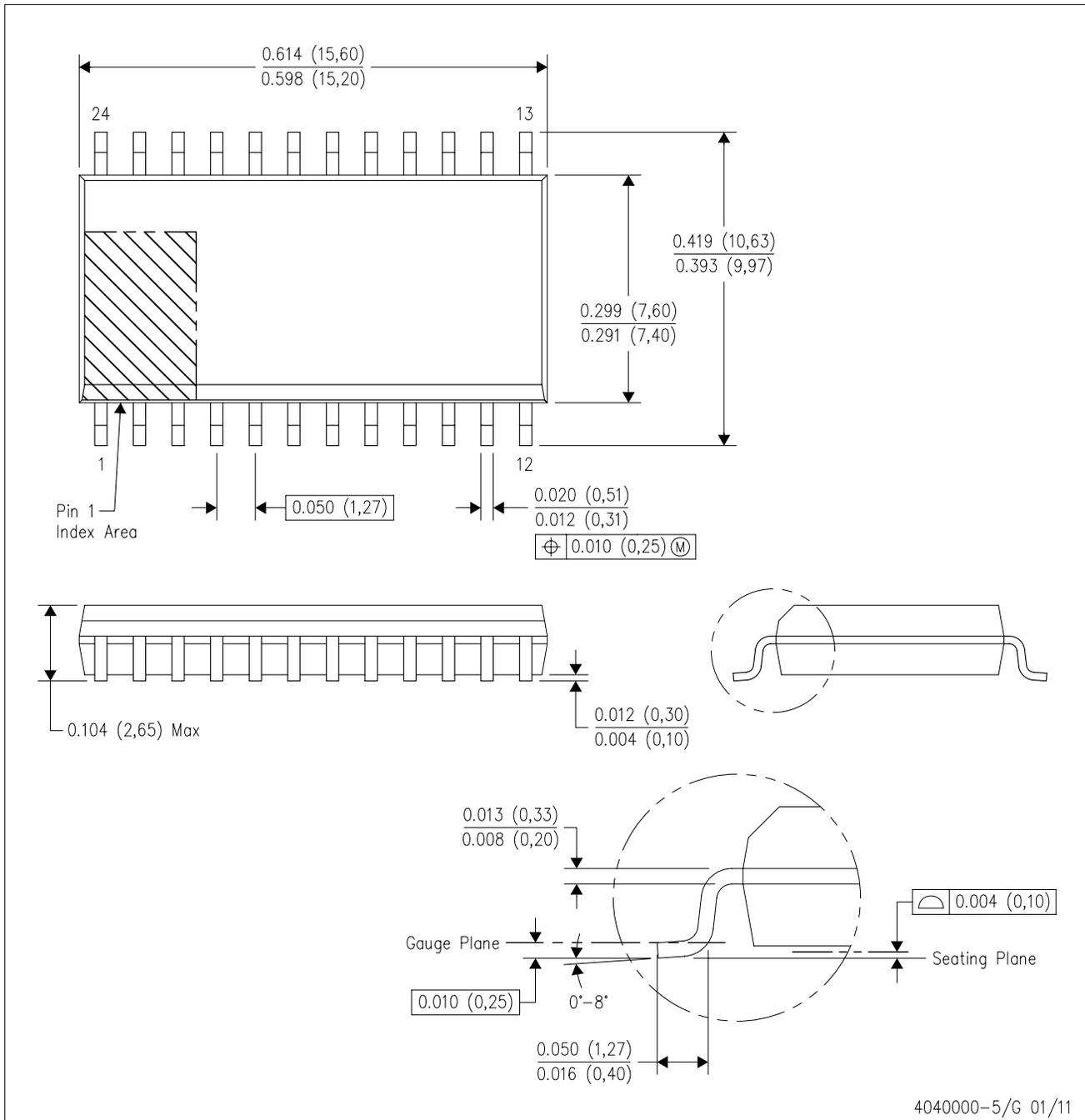
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M−1994.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
        D. Falls within JEDEC MS−013 variation AD.

FN (S-PQCC-J**)

20 PIN SHOWN

PLASTIC J-LEADED CHIP CARRIER

Seating Plane

0.004 (0,10)

0.180 (4,57) MAX
0.120 (3,05)
0.090 (2,29)
0.020 (0,51) MIN

0.032 (0,81)
0.026 (0,66)

D

D1

3   1   19

4   18

E   E1

8   14

9   13

D2/E2

D2/E2

0.021 (0,53)
0.013 (0,33)

0.050 (1,27)

0.008 (0,20) NOM

⊕ 0.007 (0,18) Ⓜ

NO. OF PINS **	D/E		D1/E1		D2/E2	
	MIN	MAX	MIN	MAX	MIN	MAX
20	0.385 (9,78)	0.395 (10,03)	0.350 (8,89)	0.356 (9,04)	0.141 (3,58)	0.169 (4,29)
28	0.485 (12,32)	0.495 (12,57)	0.450 (11,43)	0.456 (11,58)	0.191 (4,85)	0.219 (5,56)
44	0.685 (17,40)	0.695 (17,65)	0.650 (16,51)	0.656 (16,66)	0.291 (7,39)	0.319 (8,10)
52	0.785 (19,94)	0.795 (20,19)	0.750 (19,05)	0.756 (19,20)	0.341 (8,66)	0.369 (9,37)
68	0.985 (25,02)	0.995 (25,27)	0.950 (24,13)	0.958 (24,33)	0.441 (11,20)	0.469 (11,91)
84	1.185 (30,10)	1.195 (30,35)	1.150 (29,21)	1.158 (29,41)	0.541 (13,74)	0.569 (14,45)

4040005/B 03/95

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Falls within JEDEC MS-018

TEXAS INSTRUMENTS